



# **LCD MODULE**

# MODULE NO.:

# KSECB1601XXX-R02-SERIES

Customer:		
Approved by:		
Approved by	Checked by	Prepared by

# **RECORDS OF REVISION**

Part Number	Revision	Revision Content	Revised on
KSECB1601XXX-R02	1.0	First issue	Nev. 4th, 2022

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#### 1. MODULE CLASSIFICATION INFORMATION

(5) (6) (7)

# <u>KSE C B 1601 X X X - R 02</u>

(4)

① KSE: COMPONET, Ltd

(2)

② C: Character Type, G: Graphic Type

(3)

③ B: COB, G: COG

4 Display Font: 16 \* 1

⑤ LCD Mode:

(1)

 $B \rightarrow STN$ -Blue Negative  $F \rightarrow FSTN$  Positive

 $G \rightarrow STN$  Gray Positive  $Y \rightarrow STN$  Yellow Green Positive

(8) (9)

Backlight Type:

 $N \rightarrow Without backlight$   $A \rightarrow Amber LED backlight$ 

B→ Blue LED backlight G→ Green LED backlight

 $R \rightarrow Red LED$  backlight  $W \rightarrow Withe LED$  backlight

Y→ Yellow-Green LED backlight

7 LCD Polarize Type/Temperature range/View direction :

D→ Transflective, W.T, 12:00 E→ Transmissive, W.T, 6:00

P→ Reflective, W. T, 6:00 Q→ Transmissive, W.T, 12:00

Z→ Transflective, W.T, 6:00

(8) Character Bank:

A→ English / Japan B→ English / European

R→ English / Cyrillic / Portuguese / Russian

 $T \rightarrow English / Russian$   $G \rightarrow Hebrew$ 

9 Model serials no.:

#### 2. FUNCTIONS & FEATURES

• KSECB1601XXX-R02 Series LCD type:

DisplayContents :16\*1 Characters(5\*8dots)
 Driving Scheme : 1/16 Duty; 1/5Bias
 Driver IC : AIP31066L-002

• Operating Voltage : 5.0V

• Interface :4/8-bit Parallel • Operating Temperature :-20 $^{\circ}$ C -+ 70 $^{\circ}$ C • Storage Temperature :-30 $^{\circ}$ C -+ 80 $^{\circ}$ C

• RoHS Compliant

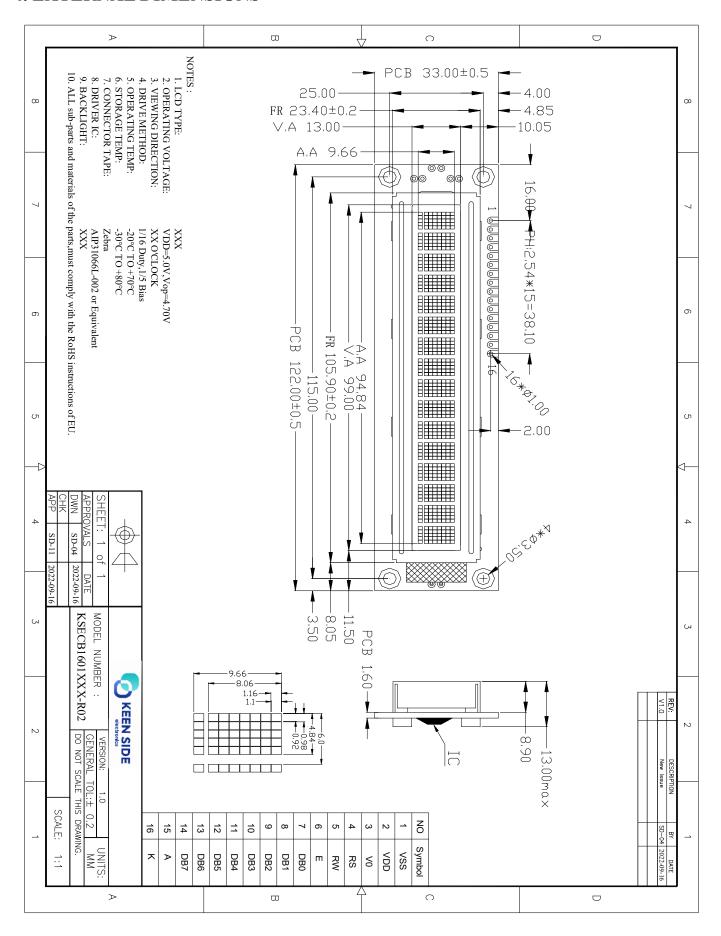
#### 3. MECHANICAL SPECIFICATIONS

• Outline Dimensions : 122.00(W) x 33.00(L) x 13.00max(H)(mm)

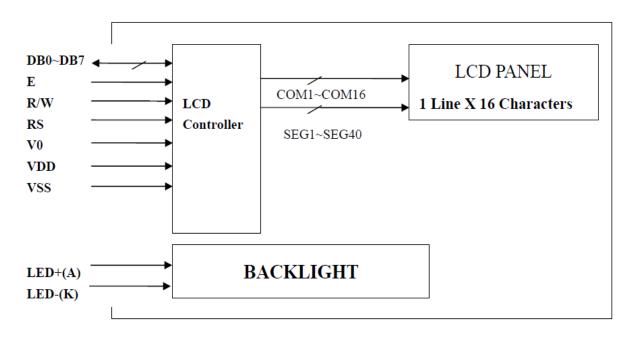
Viewing Area
 \$99.00 (W) x 13.00(L)(mm)
 Active Area
 \$94.84 (W) x 9.66 (L)(mm)
 Character size
 4.84 (W) x 8.06(L)(mm)
 Character Pitch
 6.00 (W) x 9.66 (L)(mm)
 Dot Pitch
 0.98 (W) x 1.16 (L)(mm)
 Dot Size
 0.92 (W) x 1.10 (L)(mm)

• Weight : TBD

#### 4. EXTERNAL DIMENSIONS



#### 4. BLOC'K DIAGRAM



### 6. PIN ASSIGNMENT

Pin No.	Symbol	Function						
1	VSS	Ground terminal of module.						
2	VDD	Power terminal of module						
3	V0	Power Supply for liquid crystal drive.						
		Register select						
4	RS	RS = 0···Instruction register						
		RS = 1····Data register						
		Read /Write						
5	R/W	$R/W = 1 \cdots Read$						
		R/W = 0···Write						
6	Е	Read/Write Enable Signal						
7	DB0							
8	DB1							
9	DB2	Bi-directional data bus, data transfer is performed once, thru DB0 to						
10	DB3	DB7, in the case of interface data. Length is 8-bits; and twice, thru DB4						
11	DB4	to DB7 in the case of interface data length is 4-bits. Upper four bits first						
12	DB5	then lower four bits.						
13	DB6							
14	DB7							
15	A	Anode of Backlight						
16	K	Cathode of Backlight						

#### 7. BACKLIGHT ELECTRICAL/OPTICAL SPECIFICATIONS

**Electrical/Optical Specifications (Yellow-Green)** 

Electrical optical specifications (Tenov, Green)										
ITEM	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS				
Forward Voltage	Vf	4. 0	5. 0	5. 2	V	If= 15 mA				
Reverse Current	Ir			100	μΑ	Vr=5.0 V				
Dominant wave length	λD	569	572	575	nm	If= 15 mA				
Spectral Line Half width	Δλ		25		nm	If= 15 mA				
Luminous	Lv	70			cd/m <sup>2</sup>	If= 15 mA				

**Electrical/Optical Specifications (White)** 

ITEM	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS		
Forward Voltage	Vf	4.8	5.0	5.2	V	If= 15 mA		
Reverse Current	Ir			100	μΑ	Vr=5.0 V		
Dominant wave length	X	0.26		0.30		If— 15 m A		
Dominant wave length	Y	0.26		0.30	-	If= 15 mA		
Spectral Line Half width	Δλ				nm	If= 15 mA		
Luminous	Lv	70			cd/m <sup>2</sup>	If= 15 mA		

## 8. MAXIMUM ABSOLUTE POWER RATINGS

ITEM	SYMBOL	STANDRADVALUE	UNIT
Power supply voltage(1)	VDD	-0.3~+7.0	V
Power supply voltage(2)	VLCD	VDD-10.0~VDD+0.3	V
Input voltage	VIN	-0.3~VDD+0.3	V
Operating temperature	Topr	-20~+70	${\mathbb C}$
Storage temperature	Tstg	-30~+80	$^{\circ}$

<sup>\*</sup>Voltage greater than above may damage to the Circuit.

## 9. ELECTRICAL CHARACTERISTICS

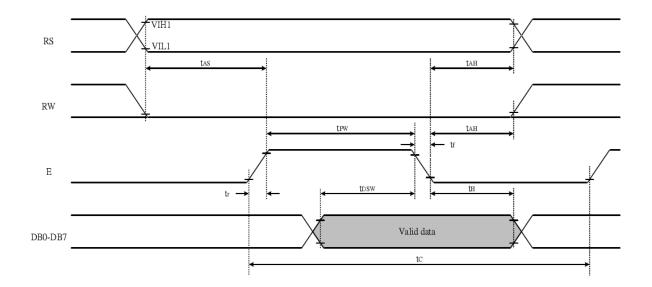
# 9-1 DC Characteristics

Item	Cymbol	Sta	andard Va	lue	Test	Unit	
Item	Symbol	MIN	TYP	MAX	Condition		
Operating Voltage	$V_{DD}$	4.8	5.0	5.2		V	
	$I_{DD1}$		TBD	1.0	Ceramic oscillation fosc=250kHz		
Supply Current	$I_{\mathrm{DD2}}$		TBD	0.6	Resistor oscillation external clock operation fosc=270kHz	mA	
LCD Driving Voltage	VLCD	4.5	4.7	4.9	V <sub>DD</sub> -V <sub>0</sub>	V	

#### 9-2 AC Characteristics

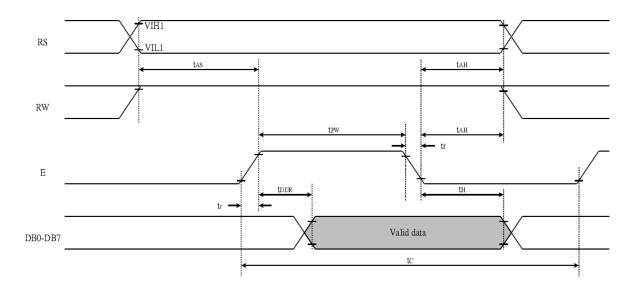
#### 9.2.1 Write mode

Characteristic	Symbol	Min	Type	Max	Unit	Test PIN
Enable Cycle Time	$t_{\rm C}$	1200			ns	Е
Enable Pulse Time	$T_{PW}$	460			ns	Е
Enable Rise/Fall Time	T <sub>R</sub> , T <sub>F</sub>			25	ns	Е
Address Set-up Time	T <sub>AS</sub>	0			ns	R/W,RS,E
Address Hold Time	Тан	10			ns	R/W,RS,E
Data Set-up Time	$T_{DSW}$	80			ns	DB0~DB7
Data Hold Time	$T_{\mathrm{H}}$	10			ns	DB0~DB7



#### 9.2.2 Read mode

Characteristic	Symbol	Min	Type	Max	Unit	Test PIN
Enable Cycle Time	$t_{\rm C}$	1200			ns	Е
Enable Pulse Time	$T_{PW}$	480			ns	Е
Enable Rise/Fall Time	T <sub>R</sub> , T <sub>F</sub>			25	ns	Е
Address Set-up Time	$T_{AS}$	0			ns	R/W,RS,E
Address Hold Time	Тан	10			ns	R/W,RS,E
Data Set-up Time	$T_{\mathrm{DDR}}$			320	ns	DB0~DB7
Data Hold Time	$T_{\mathrm{H}}$	10			ns	DB0~DB7



# 10. DISPLAY DATA RAM (DDRAM)

When the display shift operation is performed, the DDRAM Address moved as follow:

After the left shift instruction

After the right shift instruction

#### 11. INSTRUCTION TABLE

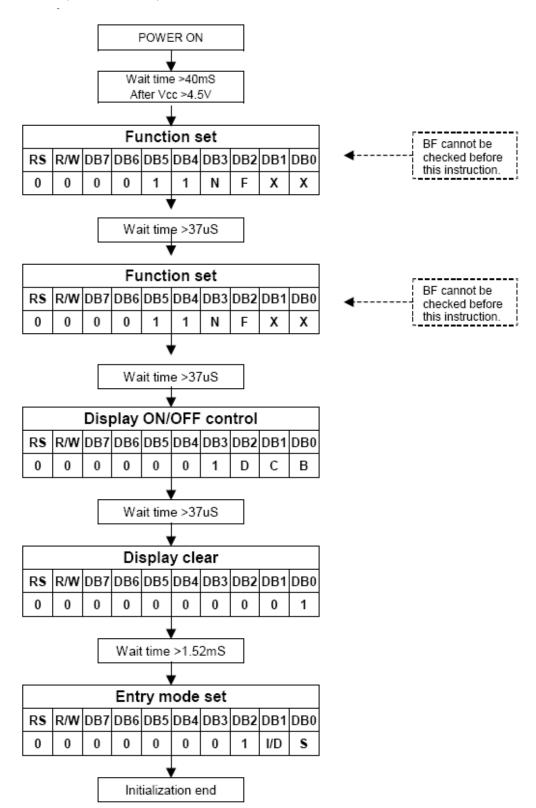
Command	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Execution time (fosc=270KHz	Remark
Clear Display	0	0	0	0	0	0	0	0	0	1	1.52ms	Write"20H" to DDRAM. And set DDRAM address to "00H" from AC
Return home	0	0	0	0	0	0	0	0	1	X	1.52ms	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.
Entry mode Set	0	0	0	0	0	0	0	1	I/D	S	37us	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.
Display on/off control	0	0	0	0	0	0	1	D	С	В	37us	D=1: entire display on C=1: cursor on B=1: cursor position on
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	x	х	37us	Set cursor moving and display shift control bit, and the direction, without changing DDRAM data.
function Set	0	0	0	0	1	DL	N	F	x	x	37us	DL: interface data is 8/4 bits N: number of line is 2/1 F: font size is 5x11/5x8
Set CGRAM address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	37us	Set CGRAM address in address counter
Set DDRAM address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	37us	Set DDRAM address in address counter
Read busy flag& address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	0us	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.
Write data	1	0	D7	D6	D5	D4	D3	D2	D1	D0	37us	Write data into internal RAM (DDRAM/CGRAM)
Read data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	37us	Read data from internal RAM (DDRAM / CGRAM)

#### Note:

Be sure the AIP31066 is not is not in the busy state (BF=00 before sending an instruction from the MPU to the AIP31066. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself. Refer to instruction table for the list of each instruction execution time.

#### 12. INITIALIZING BY INSTRUCTION

8-bit interface mode (fosc=270kHz)



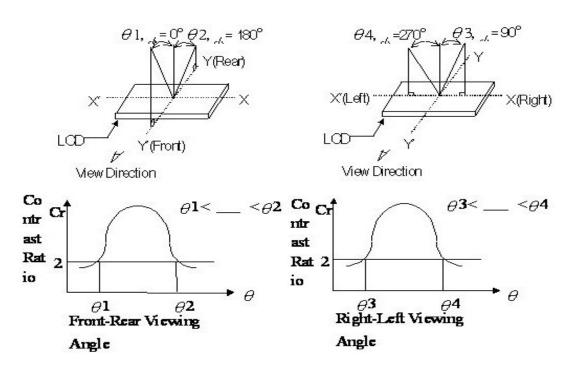
## 13. CHARACTER GENERATOR ROM

002

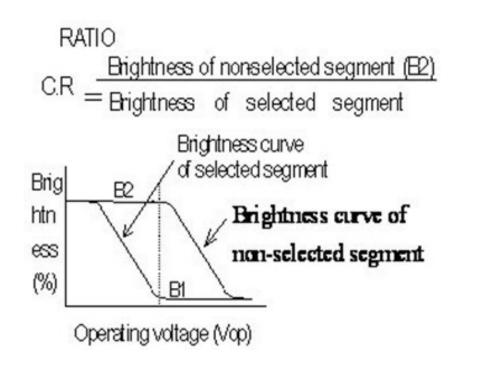
67-64 63-60	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	CG RAM (1)															×
0001	(2)												Ш			M
0010	(3)			2	В		b						1	u	Ш	W
0011	(4)		#				C.	88.			W		ы		A	1
0100	(5)			4												
0101	(6)		×											ж		
0110	(7)		8				F				×	**	W	*	Щ	
0111	(8)			Y		W	9						98			H
1000	(1)			8		×		×								
1001	(2)			9		W						×	*	**		
1010	(3)		*		J	X	J	X				×			ě	4
1011	(4)				×		×							H	9	
1100	(5)													M	ı	M
1101	(6)				×		m				b					8
1110	(7)				N		m	×					×	×		
1111	(8)						o	æ								

## 14. Optical Characteristics

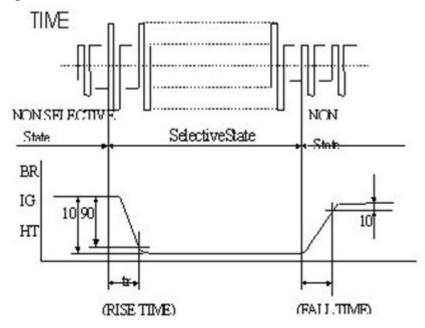
#### 14.1 Definition of Viewing Angle



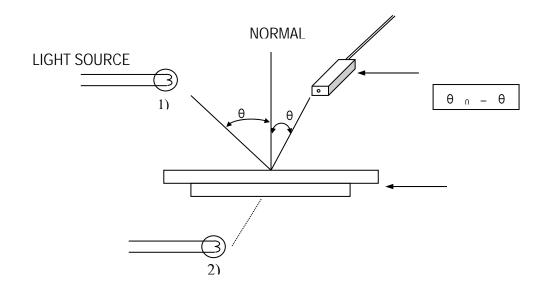
#### **14.2 Definition of Contrast**



#### 14.3 Definition of Response



#### 14.4 Measuring Instruments For Elector-optical Characteristics



#### \* Note:

- 1) Light source position for measuring the reflective type of LCD panel;
- 2) Light source position for measuring the transflective / transmissive types of LCD panel.

## 15. RELIABILITY TEST

Operating life time: Longer than 75,000 hours

(at room temperature without direct irradiation of sunlight)

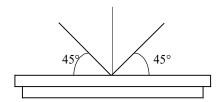
Reliability characteristics shall meet following requirements.

No.	Test Item	<b>Content of Test</b>	<b>Test Condition</b>
1	High Temperature Storage	Endurance test applying the high storage temperature for a long time	+80°C 96H
2	Low Temperature Storage	Endurance test applying the low storage temperature for a long time	−30°C 96H
3	High Temperature Operation	Endurance test applying the electric stress (voltage & current) and the thermal stress to the element for a long time	+70°C 96H
4	Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time	−20°C 96H
5	High Temperature/ Humidity Storage	Endurance test applying the high temperature and humidity storage for a long time	40°C 90%RH 96H
6	Temperature Cycle	Endurance test applying the low and high temperature cycle  -20°C 25°C 70°C 25°C  30min 5min 30min 5min  1 cycle	-20°C/70°C 5 cycles
7	Vibration Test (Package State)	Endurance test applying the vibration during transportation	10Hz-55Hz, 50m/s,15min
8	Shock Test (Package State)	Endurance test applying the shock during transportation	Half-sinewave, 100m/s, 11ms
9	Atmospheric Pressure Test	Endurance test applying the atmospheric pressure during transportation by air	40 kPa 16 H

# 16. Inspection specification

#### 16.1 Visual Inspection

- 1) Inspect under 2x20W or 40W fluorescent lamp (approximately 3000 lux) leaving 25 to 30 cm between the module and the lamp and 30 cm between the module and the eye (measuring position).
- 2) Appearance is inspected at the best contrast voltage (best contrast is adjusted considering clearness and crosstalk on screen).
- 3) Inspect the module at 45° right and left, top and bottom.
- 4) Use the optimum viewing angle during the contrast inspection.



#### 16.2 Standard of Appearance Inspection

No.	Item	Criteria					
		Round type: as per following drawing					
		$\Phi = (X+Y)$	)/2	/2 Acceptable quantity			
			Size	Zone A	Zone B		
			Ф<0.1	Any number			
			0.1<Ф<0.2	2	Any number		
<b>l</b>		X	0.2< Φ<0.25	1	Ally llullibel		
			0.25<Ф	0			
	Black spot	g ble quantity					
<b>l</b>		Length	Width	Zone A	Zone B		
1	White spot $ \begin{array}{c c} & - & \\ & L \leq 3.0 \\ & Dust & L \leq 2.5 \end{array} $	_	W≤0.02	Any number			
		L≤3.0	0.02 <w≤0.03< td=""><td>2</td><td></td></w≤0.03<>	2			
		0.03 <w≤0.05< td=""><td></td><td>Any number</td></w≤0.05<>		Any number			
		_	0.05 <w< td=""><td>As round type</td><td></td></w<>	As round type			
		L W					
		Total acceptable quantity: 3					
2	Polariser scratch	Scratch on	protective film is permi	tted			
	i dialisei sciateli	Scratch on polariser: same as No. 1					
3	Polariser bubble	$\Phi = (X+Y)/2$					

			Acceptable quantity				
		Y	Size	Zone A	Zone B		
		X	Ф<0.2	Any number			
			0.2<Ф				
			< 0.5	2	A my my man h o		
		Total	0.5<Ф <1.0	1	Any numbe		
		acce	1.0<Ф	0			
		ptabl — e quantity	: 3				
		4.1 Pin hole on W: segment with $\Phi = (A+B)/2$	segmented displ	ay			
		<b>B</b> .		Accentable qu	Acceptable quantity		
			B		Quantity		
		A	<b>A</b> W≤0	Φ<			
		-/ <b>W</b> /	W>(	).4 $\Phi \le 0.2$ $\Phi \le 1/2$	25 and		
		4.2 Pin hole o dot matri display	n Pin h	egment oles with $\Phi$ und ecceptable	er 0.10 mm ar		
	4 Segment deformation	w	.0.05	<0.05 Acceptable quar			
4		_	≤0.05.	Size	dore quantity		
•		( ₫	7	a, b<0.1	Any numbe		
		73		(a+b)/2≤0.1	Any numbe		
				0.5<Ф	2		
				<1.0	3		
		Total acceptabl	le quantity: 7				
		4.3 Segments /	dots with differe	nt width			
		Acceptable					
				Accept a≥b	$\frac{able}{a/b \le 4/3}$		
				a≥b a <b< td=""><td><math>\frac{a/b \le 4/3}{a/b &gt; 4/3}</math></td></b<>	$\frac{a/b \le 4/3}{a/b > 4/3}$		
		A	<u> </u>	u 10	W 02 713		
			layer defect				

Acceptable quantity   Size   D≤0.4   Any number   O.4 <d any="" d≤0.4="" d≤0.5="" number="" o.4<d="" ozero="" size="" th=""  =""  <=""><th colspan="5">SECD10U1AAA-KU2 SEK1ES</th><th colspan="5">Product Specification</th></d>	SECD10U1AAA-KU2 SEK1ES					Product Specification				
Size			A B			Acceptable quantity				
Degree				•			Size $\Phi \le 0.4$ Any number $0.4 < \Phi$			
10,4< ⊕ ≤1.0   5										
Size   Quantity   Q					4	0.4<Ф				
Total acceptable quantity: 7    Colour uniformity					ont	≤1.0		5		
Total acceptable quantity: 7    Colour uniformity			$\geq$		34	1.0<Ф		_		
Total acceptable quantity: 7    Solution   Colour uniformity   Level of sample for approval set as limit sample						≤1.5		3		
Total acceptable quantity: 7    Colour uniformity			<del>-  -</del>	<u> </u>		1.5<Ф		2		
Colour uniformity   Level of sample for approval set as limit sample						≤2.0				
The backlight colour should correspond to the product specification Flashing and or unlit backlight is not allowed Dust larger than 0.25 mm is not allowed Exposed wire bond pad is not allowed  (Wire bond line exposed) Dust or bubble on the resin are not allowed  No unmelted solder paste should be present on PCB Cold solder joints, missing solder connections, or oxidation are not allowed No residue or solder balls on PCB are allowed Short circuits on components are not allowed  Tray particles    Acceptable quantity			Total accepta	able quanti	ty: 7					
The backlight colour should correspond to the product specification Flashing and or unlit backlight is not allowed Dust larger than 0.25 mm is not allowed Exposed wire bond pad is not allowed  (Wire bond line exposed) Dust or bubble on the resin are not allowed  No unmelted solder paste should be present on PCB Cold solder joints, missing solder connections, or oxidation are not allowed No residue or solder balls on PCB are allowed Short circuits on components are not allowed  Tray particles    Acceptable quantity										
Backlight   Flashing and or unlit backlight is not allowed	5					-				
Dust larger than 0.25 mm is not allowed  Exposed wire bond pad is not allowed  TOB  Insufficient covering with resin is not allowed (wire bond line exposed) Dust or bubble on the resin are not allowed  No unmelted solder paste should be present on PCB  Cold solder joints, missing solder connections, or oxidation are not allowed  No residue or solder balls on PCB are allowed  Short circuits on components are not allowed  Acceptable quantity  Size Quantity  Acceptable quantity  On tray  Φ < 0.2 Any number  Φ > 0.25 4  On display  Φ ≥ 0.25 2			_		•		ct specific	ation		
Exposed wire bond pad is not allowed	6	Backlight	_		=					
COB										
exposed) Dust or bubble on the resin are not allowed   No unmelted solder paste should be present on PCB	7	COD	-	-		1 1/ 1				
No unmelted solder paste should be present on PCB Cold solder joints, missing solder connections, or oxidation are not allowed No residue or solder balls on PCB are allowed Short circuits on components are not allowed  Acceptable quantity Size Quantity  On tray	1	COB								
Cold solder joints, missing solder connections, or oxidation are not allowed  No residue or solder balls on PCB are allowed  Short circuits on components are not allowed  Acceptable quantity  Size Quantity  On tray $\Phi > 0.25$ Any number $\Phi > 0.25$ 4  On display  On display							owed			
8 PCB allowed No residue or solder balls on PCB are allowed Short circuits on components are not allowed  Acceptable quantity  Size Quantity  On tray $\Phi < 0.2$ Any number $\Phi > 0.25$ 4  On display $\Phi \ge 0.25$ 2				-	•		idation are	not		
No residue or solder balls on PCB are allowed Short circuits on components are not allowed	8	PCB			8	,				
Acceptable quantity  Size Quantity  On tray $\Phi < 0.2$ Any number $\Phi > 0.25$ 4  On display  On display		102	No residue or solder balls on PCB are allowed							
9 Tray particles $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			Short circuits on components are not allowed							
9 Tray particles $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$					antity					
9 Tray particles On tray $\Phi < 0.2$ Any number $\Phi > 0.25$ 4 On display $\Phi \ge 0.25$ 2							uantity			
On tray $\Phi > 0.25$ 4  On display $\Phi > 0.25$ 2		T				+				
I On display	9	i ray particles		On tray	Ф>0.25					
On display $L=3$ 1				1. 1	Ф ≥0.2	5	2			
				n display	L = 3		1			

#### 17. LCD MODULES HANDLING PRECAUTIONS

- Please remove the protection foil of polarizer before using.
- The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- If the display panel is damaged and the liquid crystal substance inside it leaks out, do not get any in your mouth. If the substance come into contact with your skin or clothes promptly wash it off using soap and water.
- Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarize carefully.
- To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
  - -Be sure to ground the body when handling the LCD module.
  - -Tools required for assembly, such as soldering irons, must be properly grounded.
  - -To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
  - -The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.

#### ■ Storage precautions

When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps. Keep the modules in bags designed to prevent static electricity charging under low temperature / normal humidity conditions (avoid high temperature / high humidity and low temperatures below  $0^{\circ}$ C). Whenever possible, the LCD modules should be stored in the same conditions in which they were shipped from our company.

#### 18. OTHERS

- Liquid crystals solidify at low temperature (below the storage temperature range) leading to defective orientation of liquid crystal or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subjected to a strong shock at a low temperature.
- If the LCD modules have been operating for a long time showing the same display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. Abnormal operating status can be resumed to be normal condition by suspending use for some time. It should be noted that this phenomena does not adversely affect performance reliability.
- To minimize the performance degradation of the LCD modules resulting from caused by static electricity, etc. exercise care to avoid holding the following sections when handling the modules:
  - Exposed area of the printed circuit board
  - Terminal electrode sections